



Title: METHOD OF PACKAGING A
DEVICE WITH A LEAD FRAME,
AND AN APPARATUS FORMED
THEREFROM
Application No. 09/801,339

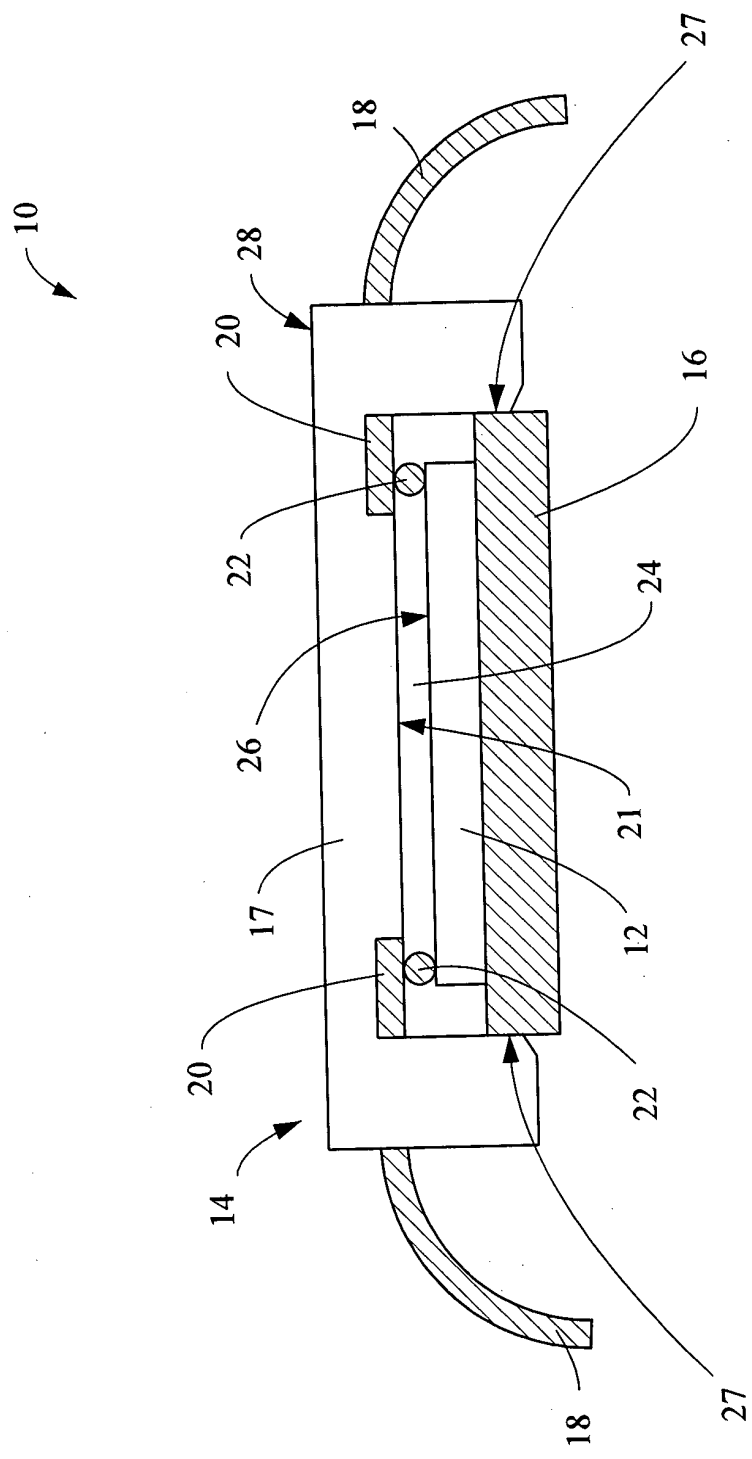


FIG. 1

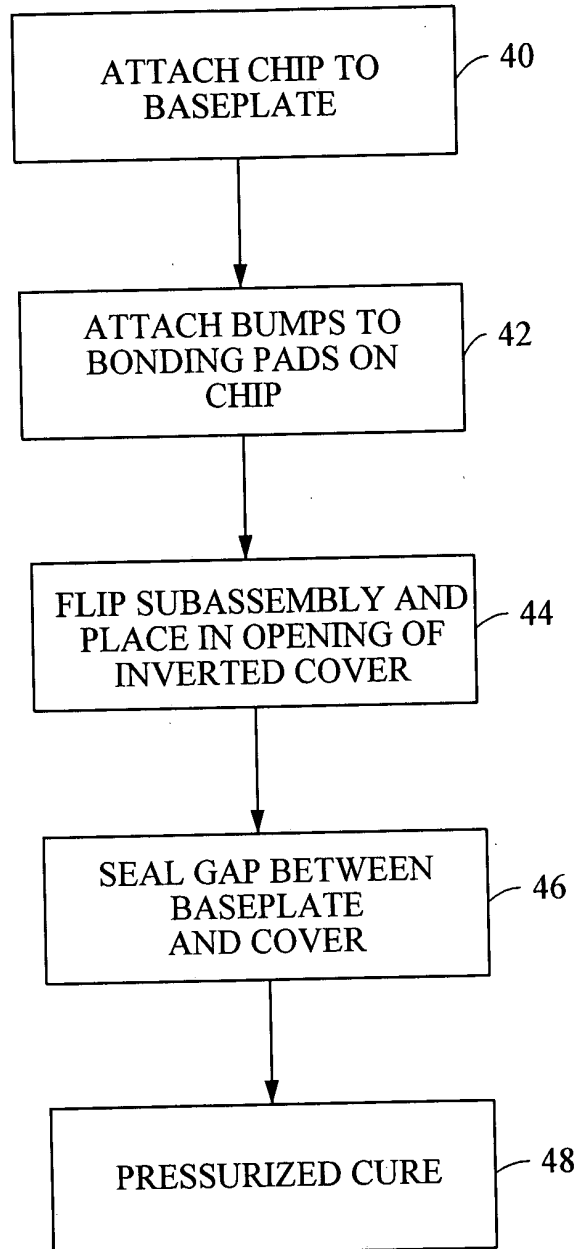


FIG. 2

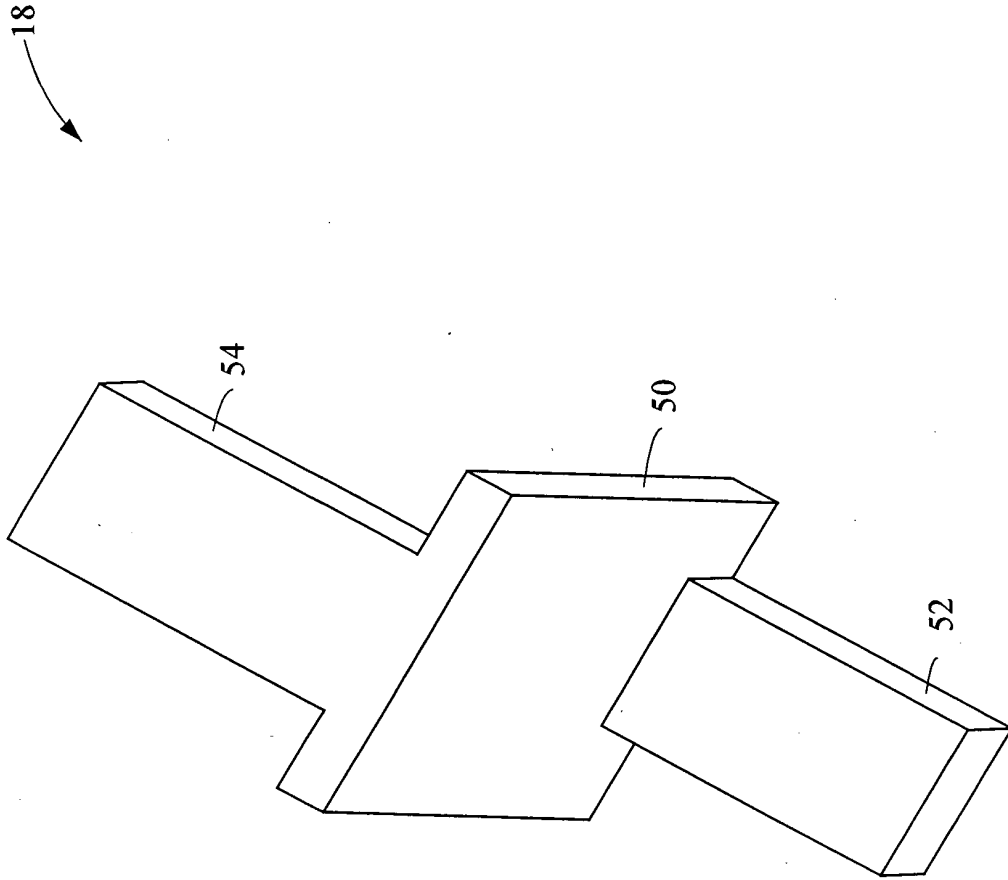


FIG. 3

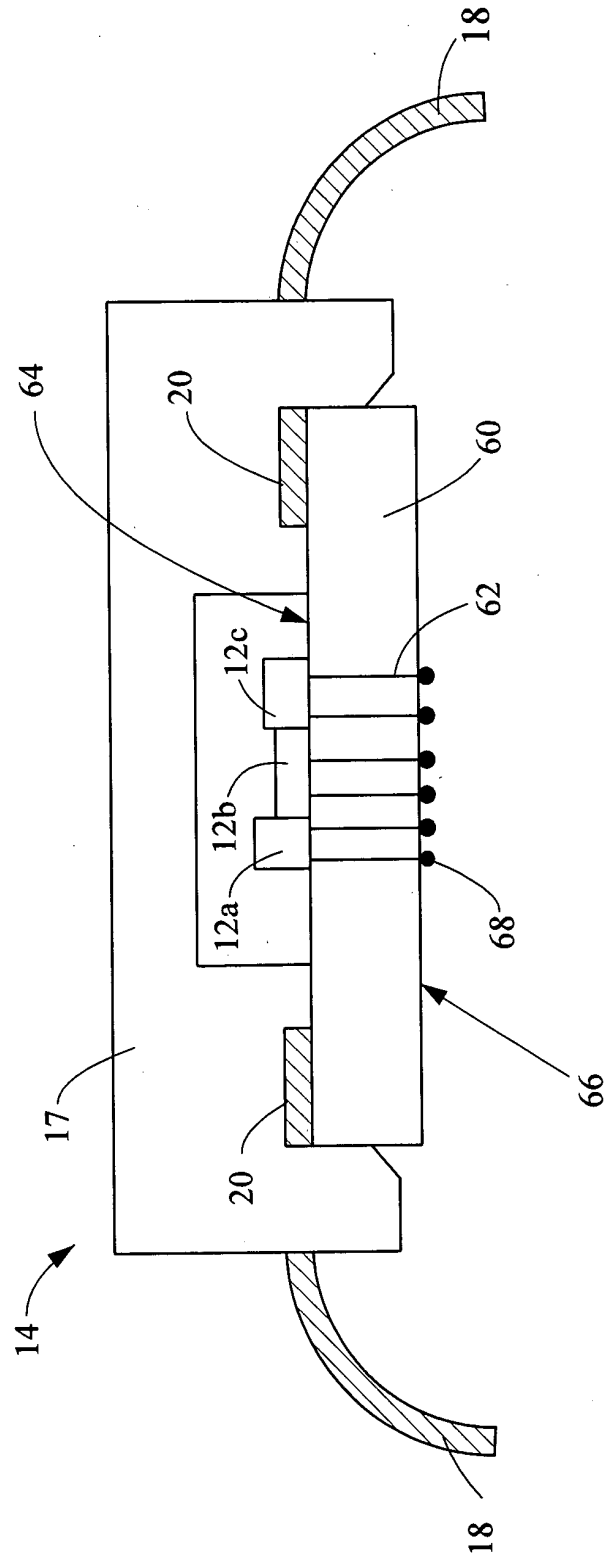


FIG. 4

$V_D = 7V$
 $I_D = 600mA$
 $V_g = -1.0V$

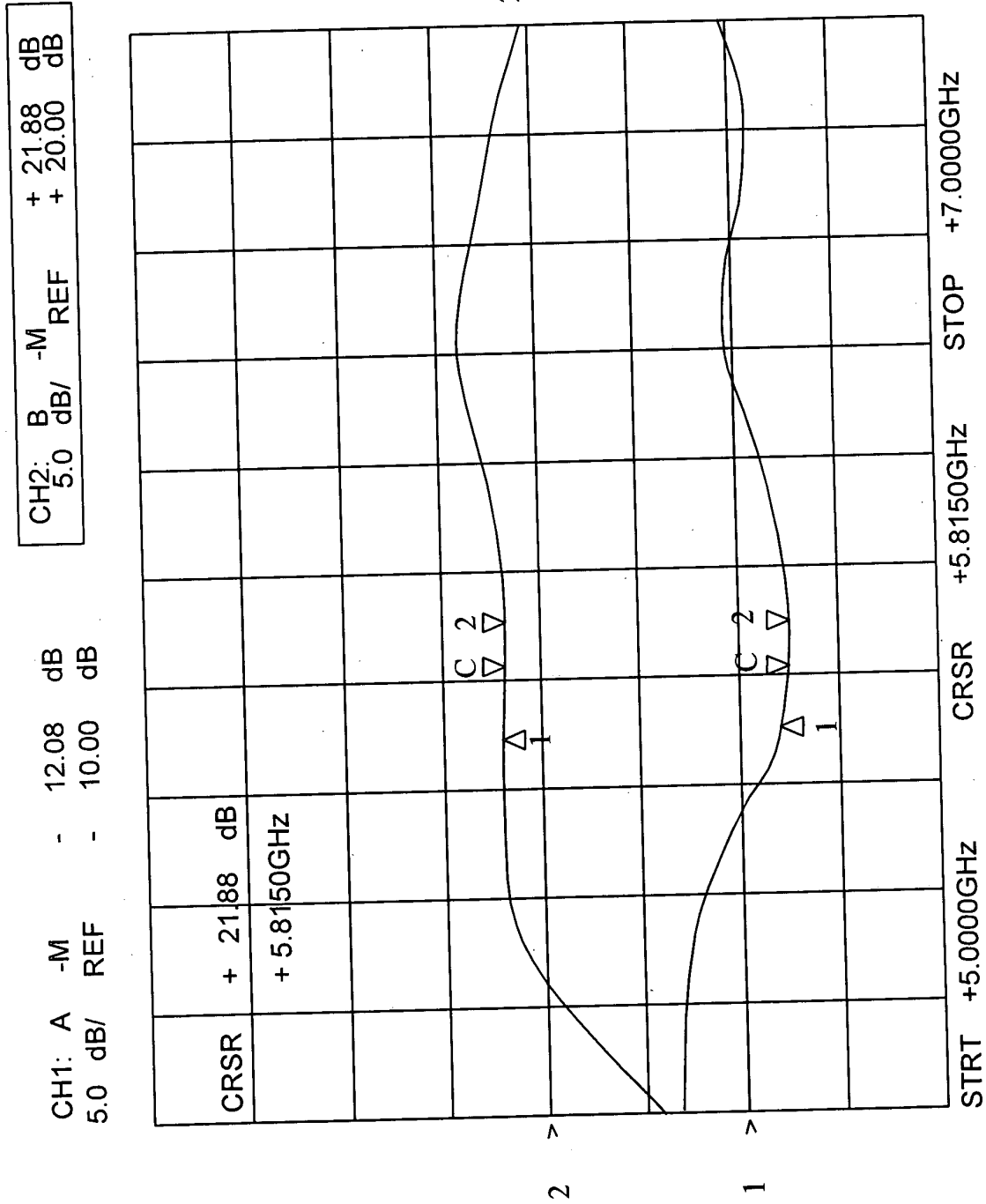


FIG. 5